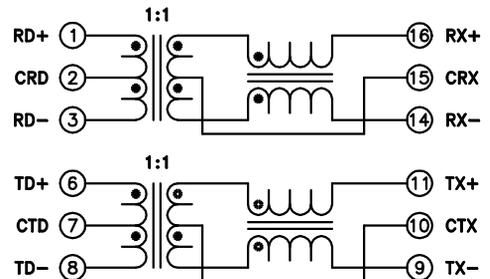
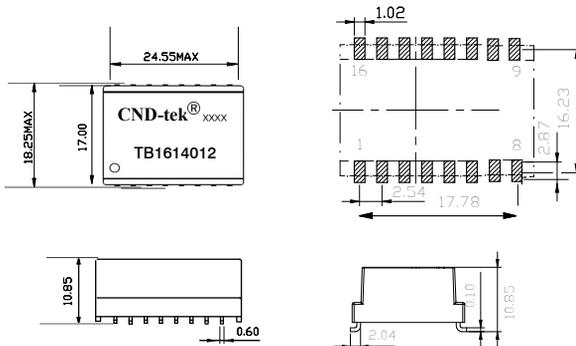


1. Compatible with various 10/100 Base-TX transceiver requiring 1:1 transmit and receive turns ratio
2. Compliant with IEEE 802.3ab standard including baseline wander compensation specification of 350μH OCL when Biased at 8mA
3. Low profile Surface Mount Packaging designed for Hi-Temp Reflow Process
4. Designed to comply with the following requirements as defined by IEC60950-1: Reinforced insulation at a working volatage of 250Vrms.
5. Designed to comply with 8mm min.creepage an clearance as defined by IEC60601-1.
6. Operating Temperature range: 0°C TO +70°C
7. Storage temperature range: -25°C TO +125°C



DIMENSIONS & SCHEMATICS

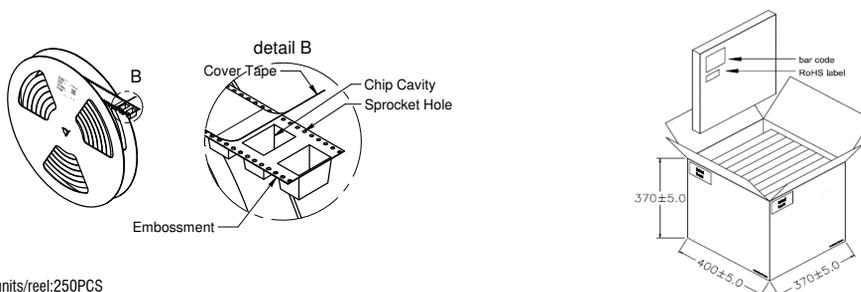


All 16 terminals must lie on a plane within .004mm of surface a after lead tinning

TECHNICAL SPECIFICATIONS

Inductance :	350 μH Min. @ 100 KHz, 100mV with 8mA DC Bias Lp(16-14) 350 μH Min. @ 100 KHz, 100mV with 8mA DC Bias Lp(11-9)
Turns Ratio(±2%):	1CT:1CT,(1-3):(16-14) 1CT:1CT,(6-8):(11-9)
Insertion Loss:	-1.2 dB Max. @ 0.5-100MHz
Return Loss:	-18dB Min. @ 0.5-30MHz -15 dB Min. @ 30-45 MHz -13 dB Min.@ 45-60 MHz -10dB Min.@ 60-80 MHz
Cross Talk:	-40 dB Min.@ 1-100 MHz
DCMR:	-33dB Min.@ 0.5-100MHz
Isolation HI-POT:	4000Vrms 1mA 60Second,4800Vrms 1mA 3Second

PACKING SPECIFICATION



1. units/reel:250PCS
2. reel/carton:3PCS
3. units/carton :750PCS